## Typical Procedure

1.	Preheat hot plates to 60°C and 100°C.	Clariant AZ 1518
2	Note: See DataPlate Hotplate Individi.	RPM1 = 2000
Z.	Clean sample in acetone, methanol, isopropanol solution at 60°C for 5 min.	RAMP1 = 2
3.		TIME1 = 1
	• Prepare two small baths (~25 ml each) of 1:4 [400K developer:DI H <sub>2</sub> 0].	RPM2 = 3000
	• Start mask aligner. See Karl Suss Mask Aligner manual.	RAMP2 = 1
	• Start spincoater. See SCS SpinCoater manual.	I   E   = 1
	<ul> <li>Program appropriate spin parameters as recommended at right.</li> </ul>	κρινις = 4000 Βαμάς = 1
4.	Remove solvent from hotplate; change hotplate temperature to 150°C.	TIME3 = 30
5.	Dry sample with compressed N <sub>2</sub> ; clean in diluted developer by dipping for 40	
	sec in first bath, 20 sec in second bath.	
	Note: Second bath will be cleaner and may be used later. Dispose of first bath.	LOR-10B
_	Prepare small bath (~25ml) for later use, and set both aside.	RPM1 = 2000
6.	Rinse sample in acetone, then methanol, then isopropanol.	RAMP1 = 2
7.	Dry with compressed $N_2$ .	1   V  = 1 $PDM2 = 2000$
8.	Place sample on spincoater chuck. (A test spin is recommended.)	$R\Delta MP2 = 3000$
9.	Cover sample completely with LOR (10B or 30B).	TIMF2 = 1
10	Press Start button and allow spin recipe to complete.	RPM3 = 4000
	Note: If resist appears on backside of sample, drop 2-3 drops of EBR	RAMP3 = 1
	remover on clean room towel and carefully glide backside of sample across	TIME3 = 30
	wetted area. Take care not to expose topside to remover.	
11	. Bake on 150°C hotplate for 5 min; change hotplate temperature to 110°C.	
12	Cool sample on cold surface for 10 sec.	RPM1 - 500
13	. Spin-test sample on spincoater.	RAMP1 = 2
14	. Cover sample completely with Clariant AZ 1518 photoresist .	TIME1 = 1
15	Press Start button, and allow entire spin recipe to complete.	RPM2 = 900
	Note: If resist appears on backside, clean with EBR remover	RAMP2 = 5
16	. Soft bake on 100°C hotplate for 45 sec.	TIME2 = 1
17.	Cool sample on cold surface for 10 sec.	RPM3 = 1000 - 1500
18	Select chrome or FeO mask and rinse pattern-side of mask with acetone.	RAMP3 = 1
19.	Dry mask thoroughly with compressed $N_2$ .	IIIVIE3 = 30 - 60

- 20. Develop sample by dipping in 1:4 developer for 40 sec, then 20 sec in a second bath.
- 21. Rinse with DI water and dry with compressed  $N_2$ .
- 22. Inspect photoresist pattern quality using a microscope.
- If pattern quality is good, hard bake on 110°C hot plate for 5 minutes.
   Note: Further develop in 10 sec intervals if needed. Otherwise, strip PR and LOR thoroughly with acetone and begin again.
- 24. Remove sample from hotplate and cool on cold surface before storing in carrier.
- 25. Turn off hotplates, aligner, spincoater and microscope.

## Clean-Up

- 1. While photoresist is hard-baking, remove glass mask from mask chuck and clean patterned side with acetone to remove any residual PR. Dry with compressed N<sub>2</sub> gas, and return to protective case.
- 2. Clean up wet bench by disposing of solvents and developer. **Note**: Never leave open solvent waste bottle in sink. This is a violation of chemical safety procedure.
- 3. Rinse glassware and used containers with DI H<sub>2</sub>O, return upside down on drying rack.
- 4. Dry bench top.

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